

SOT745-1

plastic low profile fine-pitch ball grid array package; 72 balls;
body 7 x 7 x 0.9 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA72
Package type industry code	LFBGA72
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	19-5-2004

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		6.9	-	7	7.1	mm
E	package width		6.9	-	7	7.1	mm
A	seated height		[tbd]	-	1.3	1.3	mm
A ₂	package height		0.85	-	0.9	1	mm
n ₂	actual quantity of termination		-	-	72	-	



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2. Package outline

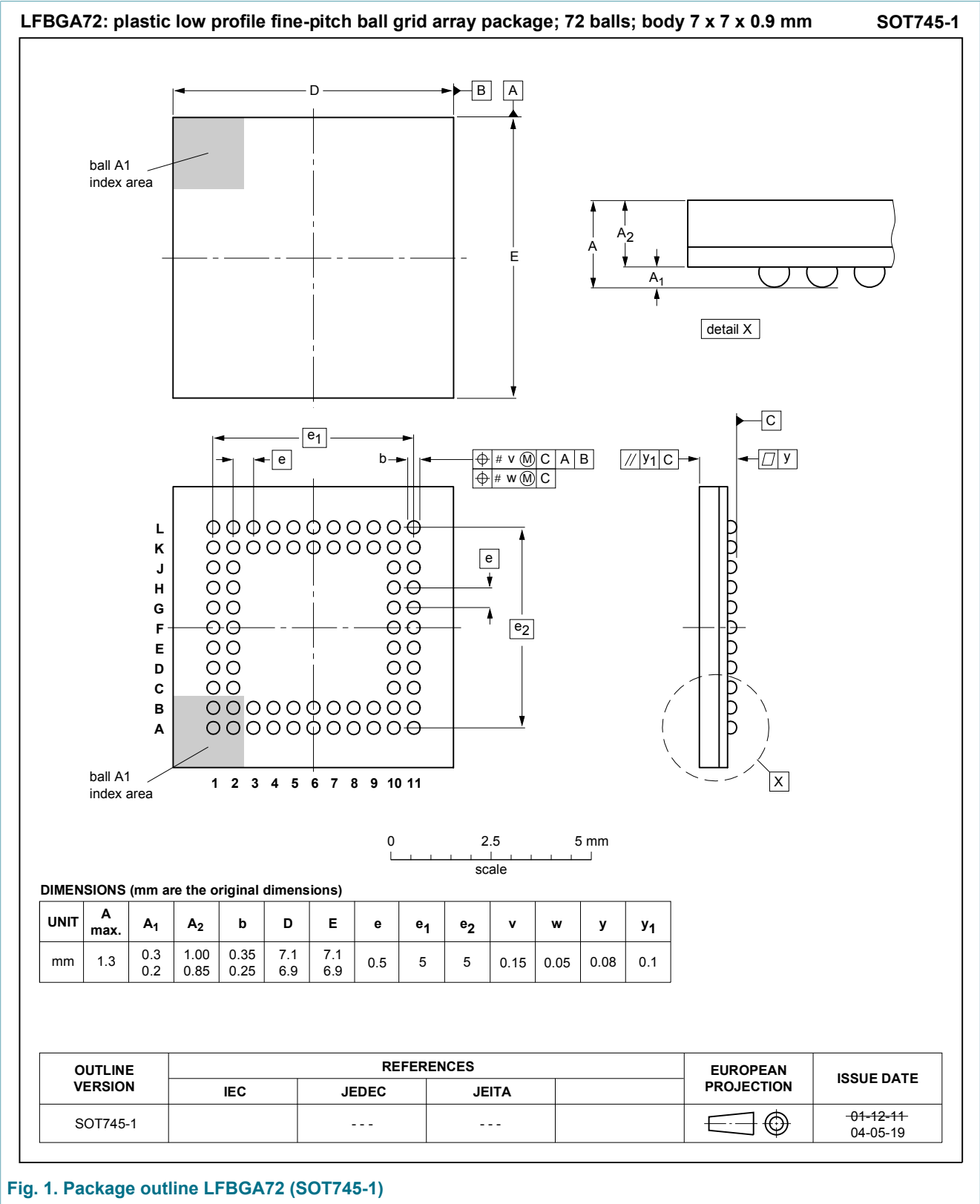


Fig. 1. Package outline LFBGA72 (SOT745-1)

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3. Soldering

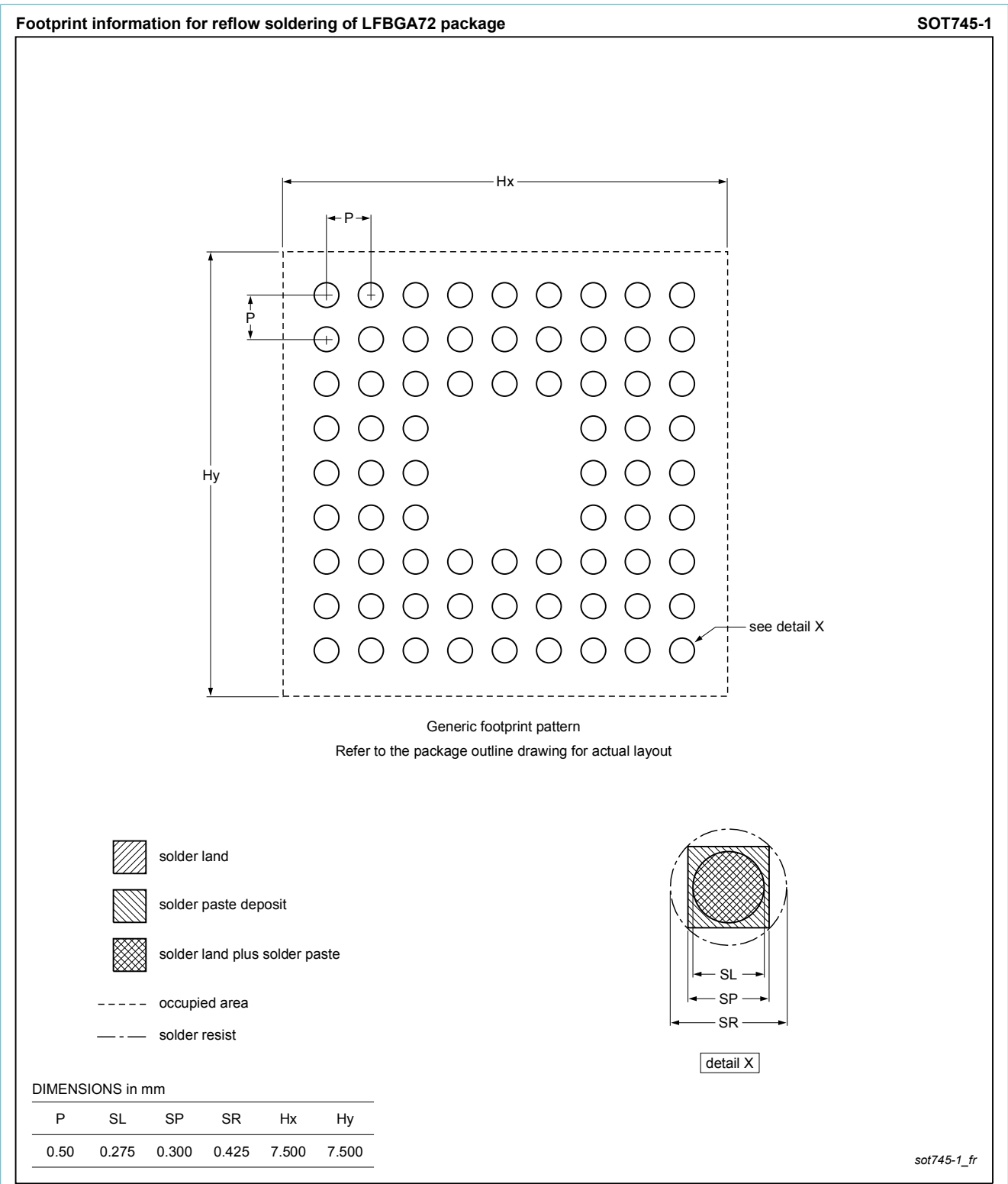


Fig. 2. Reflow soldering footprint for LFBGA72 (SOT745-1)

4. Legal information

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